

MICROELECTRONIC OUTLINES (MO)

Contents

MO-001	Dual in-line Family 7.62 mm Row Spacing
MO-002	Header Family .200" Pin Circle
MO-003	Flatpack Family 5.08 Width, 1.27 Pitch RESCINDED – Replaced by MS-033
MO-004	Flatpack Family .300 Width, .50 Pitch RESCINDED – Replaced by MS-033
MO-005	Grid Array Family .125" Pitch
MO-006	Header Family 5.842 mm Pin Circle
MO-007	Header Family 3.58mm Pin Circle - ARCHIVED
MO-008	Header Family 2.54mm Pin Circle - ARCHIVED
MO-009	Header Family 5.08mm Pin Circle - ARCHIVED
MO-010	Header Family 1.65mm Pitch - ARCHIVED
MO-011	Grid Array Family 2.54mm Pitch - ARCHIVED
MO-012	Quad Header Family 2.540mm Pitch - ARCHIVED
MO-013	Header Family 11.89mm Pin Circle - ARCHIVED
MO-014	Flange-Mounted Family Axial Lead
MO-015	Dual In Line (DIP) Family 15.24 mm Row Spacing
MO-016	Dual In Line Plastic Family .900" Row Spacing
MO-017	Axial Quad Family 2.54 mm Pitch
MO-018	Flatpack Family 10.16 mm Width, .89 Pitch
MO-019	Flatpack Family .400 Width, .50 Pitch RESCINDED – Replaced by MS-033
MO-020	Flatpack Family 12.70 mm Width, 1.27 Pitch
MO-021	Flatpack Family 15.24 mm Width, 1.27 Pitch
MO-022	Flatpack Family 17.780 mm Width, 1.27 Pitch
MO-023	Flatpack Family 22.86 mm Width, 1.27 Pitch
MO-024	Dual In Line (DIP) Family 12.70 mm Row Spacing
MO-025	Flange Mounted Family Axial Lead 12.70 Pin Circle
MO-026	Standard Dual-in-Line Family .400" Row Spacing (Plastic) .070" Lead Pitch
MO-027	Leadless Flatpack Family 1.27 mm Terminal Space
MO-028	Dual In Line (DIP) Family 5.08 mm Row Spacing
MO-029	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing
MO-030	Quad In Line (QUIP) Family 19.05/23.50 mm Row Spacing
MO-031	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing
MO-032	Flatpack Family 16.64 mm Width, 1.27 Pitch
MO-033	Quad In Line (QUIP) Family 17.78/22.86 mm Row Spacing
MO-034	Quad In Line (QUIP) Family .750/.925" Row Spacing
MO-035	Single In Line (SIP) Family
MO-036	Ceramic Side Ledged Dual In Line (DIP) Family 7.62 Row Spacing
MO-037	Ceramic Side Ledged Dual In Line (DIP) Family 10.16 Row Spacing RESCINDED – Replaced by MS-031
MO-038	Ceramic Side Ledged Dual In Line (DIP) Family 22.86 mm Row Spacing
MO-039	Ceramic Side Ledged Dual In Line (DIP) Family 22.86 mm Row Spacing
MO-040	Power Module

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MO-041	.050" Center Leadless Rectangular Chip Carrier Type F
MO-042	.050" Center Leadless Rectangular Chip Carrier Type F
MO-043	Dual In Line Package 19.05 mm Row Spacing
MO-044	Leaded Ceramic Chip Carrier .050" Center
MO-045	Single In Line Power Module
MO-046	Small Outline (SO) Package Peripheral Terminals 5.30 mm (.200") Wide Body
MO-047	Plastic Chip Carrier (PCC) Family .050" Leadspring, Square
MO-048	Plastic Flange-Mounted Header Family Multilead Registration
MO-049	Not Published
MO-050	Not Published
MO-051	Not Published
MO-052	Plastic Chip Carrier (PCC) Family .050" Leadspring, Rectangular – Replaced by MS-016
MO-053	Removed September 1988 - Replaced by MS-069
MO-054	Zig-Zag (ZIP) In Line Family 2.54mm Row Spacing
MO-055	Ceramic Single In Line (SIP) Family
MO-056	Ceramic .025" Center Chip Carrier
MO-057	Ceramic .020" Center Chip Carrier
MO-058	Dual In Line Cerdip Family .300 Row Spacing RESCINDED – Replaced by MS-030
MO-059	Small Outline (SO) Package Family 8.4 mm Body Width (Plastic)
MO-060	.040" 132 Pin Quad Flatpack
MO-061	Plastic Small Outline J-Lead (SOJ) .400 Body Family RESCINDED - Replaced by MS-027
MO-062	Ceramic Chip Carrier 0.25" Center
MO-063	Plastic Small Outline J-Lead (SOJ) .350" Body
MO-064	30 Circuit Pluggable Single Inline Package (SIP) Tabs on .100" Centers
MO-065	Plastic Small Outline J-Lead (SOJ) .300 Body Family
MO-066	.100" Center Ceramic Pin Grid Array (Small Outline)
MO-067	.100" Center Ceramic Pin Grid Array (Large Outline)
MO-068	Edge Clip SIP Module Family .100 Row Centers
MO-069	Plastic Quad Flat Pack .025" Lead Spacing (Gullwing)
MO-070	.375" Width Flatpack – NOT PUBLISHED
MO-071	Plastic Thin Lead Package
MO-072	Zig-Zag Inline Family (ZIP) 0.500" Max Seated Height
MO-073	Ceramic Top Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing
MO-074	Ceramic Bottom Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing
MO-075	.50 Center Non-Hermetic Leadless Chip Carrier Quad Series
MO-076	.050 Center Non-Hermetic Leadless Chip Carrier SO Series
MO-077	Small Outline J-lead (SOJ) .300" Body, .050" Lead Spacing
MO-078	Hermetic Flange-Mounted Header Family (Peripheral Terminals) Five Lead 2.54 Spacing
MO-079	Flanged Family Peripheral lead .125 Pitch

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Contents (cont'd)

MO-080	ZIP Module Family 0.050" Pin Centers 0.100" Row Centers
MO-081	Ceramic Quadpack Family .050" Pitch
MO-082	Ceramic Quad Flat Pack .025" Lead Spacing (Gullwing)
MO-083	.100" Center Plastic Pin Grid Array Family
MO-084	Ceramic Quad Flat Pack 0.50" Lead Spacing (Gullwing)
MO-085	.040" Center Rectangular Leadless Package (Staggered Terminals)
MO-086	Low Profile Plastic Quad Flat Pack Family .025 Lead Spacing (Gullwing)
MO-087	"J" Leaded Ceramic Cerquad package Family .040" Pitch
MO-088	Small Outline J-Lead (SOJ) .300 Body Family (MS-103 body)
MO-089	Plastic Quad Flat Pack .050" Lead Spacing (Gullwing)
MO-090	Ceramic Quadpack Family .025" Lead Spacing
MO-091	Plastic Small Outline J-Lead (SOJ) .350 Body Family
MO-092	6.35 Mm Width Cerpak Registration
MO-093	Flange-Mounted Header, 5-Lead
MO-094	TapePak Molded Carrier Ring Family
MO-095	Dual Incline (Wide Body) Plastic Family .300" Row Spacing
MO-096	Flange-Mounted Header, 7-Lead
MO-097	Flange-Mounted Family Axial Lead .500" Pin Circle
MO-098	Braze Lead Flatpack Registration
MO-099	Small Outline (SO) Family Peripheral
MO-100	Multilayer Ceramic Quad Flatpack .20 Spacing Gullwing (256 leads)
MO-101	48 Pin Flatpack, Top Brazed
MO-102	Tape Quad Flat Pack RESCINDED
MO-103	Dual-In-Line Cerdip Family .600" Row Spacing
MO-104	Ceramic Quad Flatpack 0.25" Pitch Gullwing Leadform
MO-105	Thin Small Outline J-Lead (TSOJ) .300" Body, 0.050" Lead Pitch
MO-106	Flatpack Family .535" Length, .030 Pitch
MO-107	Ceramic Multilayer Leaded Chip Carrier .050" Pitch, J-Bend
MO-108	Metric Plastic QFP Family 3.2 mm footprint
MO-109	TapePak Molded Carrier Ring Family Round Lead, "J" Form
MO-110	Round Lead, "J" form .050" Center Ceramic Chip Carrier
MO-111	Round Lead, Gullwing .050" Center Ceramic Chip Carrier
MO-112	Metric Quad Flatpack Family (Plastic) 3.9 mm Footprint
MO-113	Ceramic Quadpack Family 0.25" Lead Spacing With Ceramic Nonconductive Tie Bar
MO-114	28mm Cerquad Family Gullwing Leadform 0.65, 0.80 mm Pitch
MO-115	32 Ld. Flatpack .480" Wide
MO-116	Family of Pluggable Single Inline Packages (SIP) Tabs on .050" Centers
MO-117	Small Outline Gullead 12 mm Body 0.80 mm Lead Spacing
MO-118	Shrink Small Outline Package Family 0.25" Lead Pitch .300" Wide Body
MO-119	Plastic Small Outline (SO) Package Family With .300" Body Width
MO-120	Plastic Small Outline (SO) Package Family With .350" Body Width

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Contents (cont'd)

MO-121	Plastic Small Outline (SO) Package Family With .330" Body Width
MO-122	R-PDIP-T Thin Dual In Line Family .300" Row Spacing (Plastic)
MO-123	Small Outline J-Lead, 12 mm Body 0.80 mm Lead Spacing
MO-124	Small Outline J Lead (SOJ) 12.70 mm Body 1.27 mm Lead Spacing
MO-125	Ceramic Quad Flatpack .025" Pitch Gullwing Leadform
MO-126	Leadless Small Outline Chip Carrier .050" Center
MO-127	Power Dual Inline
MO-128	Ceramic PGA Staggered (Large Outline) .100" Carrier
MO-129	Top Brazed Ceramic Leaded Chip Carrier (.020" Lead Pitch) with Plastic
MO-130	Non-Conductive Tie Bar
MO-131	Top Brazed Ceramic Leaded Chip Carrier (.025" Lead Pitch) with Plastic
MO-132	Thin Small Outline Package 7.62mm Body Family RESCINDED – Replaced by MS-025A
MO-133	Thin Small Outline Package Family 10.16mm Body RESCINDED - Replaced by MS-024
MO-134	Ceramic Quad Flatpack Family (CQFP) 0.50 mm Lead Pitch with Ceramic Nonconductive Tie Bar
MO-135	Thin Small Outline Package (TSOP II) 12.70 mm Body Family
MO-136	RESCINDED - Replaced by MS-026
MO-137	R-PDSO-G/SSOP-INCH Shrink Small Outline Package Family, .025" Lead Pitch .150" Wide Body
MO-138	16 Lead Flange Mounted Ceramic Power Pkg. (Type 1), R-CDFM-T16
MO-139	16 Lead Flange Mounted Ceramic Power Pkg. (Type 2), R-CDFM-T16
MO-140	18 Lead Flange Mounted Ceramic Power Pkg., R-CDFM-T16
MO-141	Vertical Surface Mount Package 0.50 mm Lead Pitch, R-PSIP-X24
MO-142	Thin Small Outline Package Type I, S-PDSO-G/TSOP
MO-143	RESCINDED - Replaced by MS-029
MO-144	Leadless Small Outline Ceramic Chip Carrier R-CDCC-N
MO-145	Ceramic PGA, S-CPGA-B
MO-146	Ceramic Flatpack Family R-GDFP-F
MO-147	Ceramic SOJ Chip Carrier .415" Body R-CDSO-J
MO-148	Ceramic MCM Family, S-CQFP
MO-149	Tape Ball Grid Array S-XXGA-N/TBGA
MO-150	Plastic SSOP 5.3 mm Body Width, R-PDSO-G
MO-151	Plastic Ball Grid Array Family RESCINDED – Replaced by MS-034
MO-152	Plastic SSOP R-PSDO-G/SSOP
MO-153	Plastic thin SSOP R-PDSO-G/TSSOP
MO-154	Shrink Small Outline Pkg. Family 0.4 mm and .5 mm lead pitch, 3.9 mm body width
MO-155	Plastic Small Outline (SOP), 5-Lead
MO-156	Ceramic BGA Square
MO-157	Ceramic BGA Rectangular

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MO-158	Ceramic CGA Square
MO-159	Ceramic CGA Rectangular
MO-160	72-pin DIMM
MO-161	100 and 168-pin DIMM
MO-162	Plastic Flat Pack/heat Slug Pkg 8 mm pitch 48 leads
MO-163	RESCINDED – Replaced by MS-028A
MO-164	Plastic SO 9.9 mm body width R-PDSO-G
MO-165	Plastic SOJ 10.15mm body width, .8mm pitch R-PDSO-J
MO-166	Plastic SO with Heat Slug, 20, 24, 30, 36 leads
MO-167	DIMM 1.27 mm Lead Centers 128-Pins
MO-168	Plastic Isolated Flange-Mounted Header
MO-169	Plastic Surface Mount Header
MO-170	68-Pin Card
MO-171	88-Pin Card
MO-172	112 & 300 Pin DIMM 1.27 mm pitch
MO-173	Thin Quad Heat Spreader Family
MO-174	Plastic SO 70-pin .8 mm pitch
MO-175	Plastic SOP 12.6 mm body, 1.27 mm pitch
MO-176	Ceramic Zig Zag
MO-177	200 Pin Small Outline Dual In Line Memory Module (DIMM) Family, 0.65mm Pitch RESCINDED-
MO-178	5-pin SOT
MO-179	278-pin DIMM
MO-180	Plastic SOP 13.3 mm body
MO-181	Plastic Metric SOJ 16 mm wide 40-pin
MO-182	Metric TSOP II 16 mm body width, 40, 62 leads
MO-183	TSOP I .55 mm pitch, 28-leads
MO-184	Small Outline Heat Slug
MO-185	72 pin Staggered Dual Inline Module (SDIM)
MO-186	Floppy Disk Card (FDC)
MO-187	8-lead TSSOP
MO-188	Power PQFP with Heat Slug
MO-189	Plastic QFP Heat Slug
MO-190	144 pin Small Outline DIMM
MO-191	160 pin DIMM
MO-192	Low Profile BGA Family
MO-193	6-lead Thin SO Package
MO-194	Plastic Thin Shrink Small Outline
MO-195	Thin Fine Pitch BGA 0.5 pitch
MO-196	Plastic Leadless SO Package
MO-197	Ultra Thin SO No lead 0.5 mm pitch

MICROELECTRONIC OUTLINES (MO)**Contents (cont'd)**

MO-198	Plastic QFPO 3-tier family
MO-199	Low Profile SOJ
MO-200	Stacked SOJ 2 high/4 high
MO-201	Stacked TSOP II 2 high/4 high
MO-202	Vertical Zig Zag 0.40 mm lead pitch
MO-203	Shrink SOT 5 or 6 pins
MO-204	Thermally Enhanced Plastic QFP
MO-205	Low Fine Pitch BGA 0.80 mm Family
MO-206	184 pin DIMM for DDR
MO-207	Rectangular Chip Size, FBGA Family
MO-208	Thin Fine Pitch Plastic QFP No-Lead
MO-209	Thin Shrink Small Outline No-Lead
MO-210	Rectangular TFBGA
MO-211	Die Size BGA
MO-212	Rectangular PQF 1.0mm Thick Body
MO-213	Horizontal Staggered Surface Mount
MO-214	144 pin Micro DIMM
MO-215	SDRAM Dual In Line Memory Module Family 1.0mm Contact Centers (210 Pins)
	INACTIVATION NOTICE
MO-216	TFBGA 1.0 mm and 0.8 mm Pitch
MO-217	Very Very Thin Quad Bottom Terminal Chip Carrier Family
MO-218	Plastic Flange-Mounted Staggered Header Family
MO-219	Low Profile Fine Pitch Ball Grid Array Family
MO-220	Thermally Enhanced Plastic Very Thin and Very Very Thin Pitch QFP No-Lead
MO-221	Extremely Thin Profile Two Row Cavity Down 0.50mm
MO-222	Pitch Ball Grid Array Family
MO-223	Very Thin Profile Fine Pitch Land Grid Array Family 0.50/0.65mm Pitch SQ/RECT
MO-224	200 Pin DDR S O DIMM 0.60 mm Lead Centers
MO-225	Very Thin Profile, Fine Pitch, Ball Grid Array Family 0.50/0.65 mm Pitch, SQ/RECT
MO-226	Plastic Small Outline Heatslug Package 7.5 mm Body Wide, 1.0 mm Lead Pitch
MO-227	DDR SRAM DIMM 1.00 mm Contact Centers INACTIVATION NOTICE
MO-228	Thin, Fine-Pitch Ball Grid Array, Dual Pitch (Square)
MO-229	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Dual Flat No Lead
MO-230	Plastic Small Outline with Exposed Heat Sink
MO-231	Plastic Surface Mounted Header Family 21.50 body Width, 1.40 Lead Pitch
MO-232	Low Profile Plastic Dual Flat No Lead Package
MO-233	Rectangular Die-Size, Fine Dual Pitch Ball Grid Array Family
MO-234	Low Profile Rectangular Ball Grid Array Family
MO-235	Header Family Surface Mounted (Peripheral Terminals)
MO-236	Plastic Ultra Thin Small Outline, No Lead Package
MO-237	DDR II SDRAM Dual Inline Memory Module (DIMM Family, 1.00mm Contact Centers)

MICROELECTRONIC OUTLINES (MO)**Contents (cont'd)**

MO-238	Stacked TSOP II Package Family (2 High)
MO-239	Thermally Enhanced Plastic Very Thin Dual Row Fine Pitch Quad Flat No Lead Package
MO-240	Thermally Enhanced 8 Lead 1.27 & 0.65MM Pitch, Low Profile Plastic Dual Flat No Lead Package
MO-241	Dual Compatible Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package
MO-242	Rectangular Die-Size, Stacked Ball Grid Array Family, 0.80mm Pitch
MO-243	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Bumped Quad Flat No lead Package
MO-244	244 Pin DDR2 Mini DIMM 0.60 Lead Centers
MO-245	High Profile Plastic Thermally Enhanced Enlarged Pitch Dual Flat No Lead Package
MO-246	Rectangular Fine Pitch Thin Ball Grid Array 0.65 mm Pitch
MO-247	Plastic Quad No-Lead Staggered Multi-Row Packages
MO-248	Thermally Enhanced Plastic Ultra Thin and Extremely Thin Fine Pitch Quad Flat No Lead Package
MO-249	Thin SO Package 8.89mm Body Family
MO-250	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Bumped Quad Flat No Lead Package
MO-251	Thermally Enhanced Plastic Very Thick Quad Flat No Lead Package
MO-252	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Dual Small Outline Non-Leaded Package
MO-253	16 Lead Screw Mount Power Package
MO-254	Thermally Enhanced Plastic Low and Thin Profile Fine Pitch Quad Flat No Lead Package
MO-255	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Quad Flat Small Outline Non-Leaded Package
MO-256	FB DIMM Family 1.00mm Contact Centers
MO-257	Plastic Fine Pitch Quad No-Lead Staggered Two Row Thermally Enhanced Package Family
MO-258	200 PIN DDR Mini DIMM 0.60 Lead Center
MO-259	Very Very Thin Small Outline Package Family
MO-260	DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers
MO-261	Thick & Very Thick Fine Pitch Rectangular Ball Grid Array Family 0.80mm Pitch
MO-262	Thermal Enhanced (Top Side) Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package
MO-263	Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package
MO-265	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package Including Corner Terminals
MO-266	Very Thin, Fine-Pitch, Stackable Ball Grid 0.50 mm Ball Pitch Array Family
MO-267	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package
MO-268	204 Pin DDR3 S.O. DIMM 0.60 Lead Centers
MO-269	DDR3 SDRAM DIMM 1.00mm Contact Centers

MICROELECTRONIC OUTLINES (MO)**Contents (cont'd)**

MO-270	Extra Thin Profile, Fine Pitch, Internal Stacking Module (ISM) With Single Interconnect Array 0.75/0.80 mm Pitch SQ/RECT
MO-271	Exposed Pad Plastic Small Outline Family 7.60 mm Body Width
MO-272	Low Profile Exposed Pad Plastic Small Outline Family 3.90mm Body Width
MO-273	Upper POP Package, Square, Fine Pitch, Ball Grid Array (0.65 and 0.50 mm Pitch)
MO-274	DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family 0.8 Lead Centers
MO-275	Low Profile, Fine Pitch Ball Grid Array Family (SQ)
MO-276	Low Profile, Rectangular Fine Pitch BGA 0.50mm Pitch LFR-XBGA
MO-277	13 Pin Full Size MultimediaCard (MMC) Outline-MMCplus 32 X 24 X 1.4mm
MO-278	13 Pin Reduced Size MultimediaCard (MMC) Outline-MMCmobile 18 X 24 X 1.4mm
MO-279	10 Pin Micro Size MultimediaCard (MMC) Outline-MMCmicro 14 X 12 X 1.1mm
MO-280	Ultra Thin and Very, Very Thin Profile, Fine Pitch Ball Grid Array Family (SQ.)
MO-281	DDR2 SDRAM DIMM (Dual Inline Memory Module) Family, Flex-Based, 1.00mm Contact Centers
MO-282	FB DIMM Family, Flex Based, 1.00 mm Contact Centers
MO-283	Plastic Super-Thin And Die-Thin Profiles RFID Dipole Straps
MO-284	Thin, Fine-Pitch, Rectangular Dual Pitch Ball Grid Array Family 0.80mm x 1.00mm Pitch
MO-285	Very Thin Fine-Pitch Ball Grid Array Family Rectangular 0.50/0.65/0.80 mm Pitch
MO-286	Plastic Small Outline, Wide Body SOIC, 7.5 Body Width, 0.65 Pitch
MO-287	Small Scale, Plastic, Ultra, Extra and Super Thin, Fine Pitch, Dual Small Outline, No Lead Package
MO-288	Small Scale Plastic Ultra Extra and Super Thin Fine Pitch Quad Flat No Lead Package (With Optional Thermal Enhancements)
MO-290	DDR3 SDRAM DIMM Family Flex-Based, 1.00mm Contact Centers
MO-291	Very Thin Fine Pitch Plastic Quad Flat Package 2.00mm Footprint
MO-292	Very Thin Fine Pitch Plastic Quad Flat Package, 2.00mm Footprint
MO-293	Plastic, Ultra, Extra and Super Thin Fine Pitch Dual Small Outline, Flat, Leaded Package
MO-294	Very Thin Profile, Fine Pitch, SQ Bump Grid Array Family
MO-295	Thin Profile Interstitial Fine Pitch Ball Grid Array Family (SQ)
MO-296	Scalable Quad Flat No-Lead Packages, Square and Rectangular
MO-297	SLIM LITE SSD Assembly
MO-298	Thin, Very-Thin, Very Very Thin Profile Fine Pitch Ball Grid Array Family 0.40 mm Pitch
MO-299	Surface Mount Power Package
MO-300	mSATA SSD Assembly
MO-301	Standard & Low, Fine Pitch Rectangular BGA Family 0.65mm Pitch
MO-302	Very Thin Fine-Pitch Fully Overmolded Stackable Ball Grid Array Family 0.4mm Ball Pitch
MO-304	100/170 Ball Grid Array Family Rectangular 1.0mm Pitch

MICROELECTRONIC OUTLINES (MO)

Contents (cont'd)

MO-306 Flange Mounted Family Surface Mount (Peripheral Terminals)